

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled SEMICONDUCTOR MEMORY DEVICE AND ITS CONTROL METHOD the specification of which

is attached hereto.

X was filed on July 19, 2006 as Application Serial No. 10/586,658
and was amended on _____.

X was described and claimed in PCT International Application No. PCT/JP2005/000832 filed on January 24, 2005 and as amended under PCT Article 19 on _____.

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I hereby claim priority under 35 USC 119 to Japanese Patent Application No. 2004-017348 filed on January 26, 2004.

I acknowledge the duty to disclose information which is material to patentability as defined in 37 CFR 1.56, including for continuation-in-part applications, material information which became available between the filing date of the prior application and the national or PCT international filing date of the continuation-in-part application.

Authorization To Permit Access To Application by Participating Offices

☒ If checked, the undersigned hereby grants the USPTO authority to provide the European Patent Office (EPO), the Japan Patent Office (JPO), and any other intellectual property offices in which a foreign application claiming priority to the above-identified application is filed access to the above-identified application. See 37 CFR 1.14(c) and (h). This box should not be checked if the applicant does not wish the EPO, JPO, or other intellectual property office in which a foreign application claiming priority to the above-identified application is filed to have access to the application.

In accordance with 37 CFR 1.14(h)(3), access will be provided to a copy of the application-as-filed with respect to: 1) the above-identified application, 2) any foreign application to which the above-identified application claims priority under 35 USC 119(a)-(d) if a copy of the foreign application that satisfies the certified copy requirement of 37 CFR 1.55 has been filed in the above-identified US application, and 3) any U.S. application from which benefit is sought in the above-identified application.

In accordance with 37 CFR 1.14(c), access may be provided to information concerning the date of filing the Authorization to Permit Access to Application by Participating Offices.

I hereby appoint the practitioners associated with Customer Number 22893 as my/our attorney(s) or agent(s) to prosecute this application and to transact all business in the United States Patent and Trademark Office connected therewith.

Address all telephone calls to Randolph A. Smith at telephone number 202-530-5900

Address all correspondence to the address associated with **Customer Number 22893**, which is the address listed below:

Randolph A. Smith, Smith Patent Office, 1901 Pennsylvania Ave., N.W., Suite 901,
Washington, D.C. 20006-3433 (Fax: 202-530-5902)

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under 18 U.S.C. 1001 and that such willful false statements may jeopardize the validity of the application or any patents issued thereon.

Full Name of Inventor: Takuji MAEDA

Inventor's Signature: Takuji Maeda Date: June 30, 2008

Residence Address: Osaka, Japan

Citizen of: Japan

Post Office Address: c/o Matsushita Electric Industrial Co., Ltd.
1006, Oaza Kadoma, Kadoma-shi, Osaka 571-8501 Japan

Full Name of Inventor: Shinji INOUE

Inventor's Signature: Shinji Inoue Date: June 30, 2008

Residence Address: Osaka, Japan

Citizen of: Japan

Post Office Address: c/o Matsushita Electric Industrial Co., Ltd.
1006, Oaza Kadoma, Kadoma-shi, Osaka 571-8501 Japan

Full Name of Inventor: Shoichi TSUJITA

Inventor's Signature: Shoichi Tsujita Date: June 30, 2008

Residence Address: Kyoto, Japan

Citizen of: Japan

Post Office Address: c/o Matsushita Electric Industrial Co., Ltd.
1006, Oaza Kadoma, Kadoma-shi, Osaka 571-8501 Japan

Full Name of Inventor: Yoshiho GOTOH

Inventor's Signature: Yoshiho Gotoh Date: June 30, 2008

Residence Address: Osaka, Japan

Citizen of: Japan

Post Office Address: c/o Matsushita Electric Industrial Co., Ltd.
1006, Oaza Kadoma, Kadoma-shi, Osaka 571-8501 Japan

Full Name of Inventor: Jun OHARA

Inventor's Signature: Jun Ohara Date: July 3, 2008

Residence Address: Ehime, Japan

Citizen of: Japan

Post Office Address: c/o Matsushita Electric Industrial Co., Ltd.
1006, Oaza Kadoma, Kadoma-shi, Osaka 571-8501 Japan

Full Name of Inventor: Kiminori MATSUNO

Inventor's Signature: Kiminori Matsuno Date: June 30, 2008

Residence Address: Osaka, Japan

Citizen of: Japan

Post Office Address: c/o Matsushita Electric Industrial Co., Ltd.
1006, Oaza Kadoma, Kadoma-shi, Osaka 571-8501 Japan

Full Name of Inventor: Kazuaki TAMURA

Inventor's Signature: Kazuaki Tamura Date: June 30, 2008

Residence Address: Osaka, Japan

Citizen of: Japan

Post Office Address: c/o Matsushita Electric Industrial Co., Ltd.
1006, Oaza Kadoma, Kadoma-shi, Osaka 571-8501 Japan